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Mounts All Standard Applications, with Custom Adaptations Available

1. Pressure-adjustable roller and platen process virtually any material, even thin or brittle substrates.
2. Controlled-temperature platen and tension adjustment bars provide optimal tape application conditions for standard ("blue") and UV curable dicing tape.
3. Excess tape accurately and safely trimmed from frame using circular cutter.
4. Static eliminator option removes electrical charges from dicing tape. ESD wrist-strap socket grounds operator to protect static sensitive devices during mounting process.
5. UV curable dicing tape easily applied using UV tape backing removal option.
6. Non-contact chucks (custom-made, per application requirements) available for protecting materials with sensitive surfaces. Non-contact chuck supports wafer edges, while "pillow" of compressed air supports wafer face during tape application.
7. Custom features, by request:
 - Special-design chucks for non-standard wafer/frame/tape combinations and applications.
 - Wafer x,y Centering and Theta Alignment options (reduce dicing system alignment setup time).

MWM-850/MWM-853 Options

1. UV tape backing remover - ejects UV tape backing from system to facilitate waste material management.
2. ESD eliminator - ionizer bar eliminates electrostatic charges on mounting tape to protect ESD-sensitive devices.
3. Non-contact chuck (custom-manufactured, per application) - reduces mechanical contact between chuck and wafer during mounting process to protect sensitive wafer lithography surface.
4. Wafer alignment mechanism: x,y centering and Theta alignment (custom manufactured, per application requirements) - centers wafer on wafer frame and provides optical Theta angle adjustment for high repeatability mounting results.
5. Custom-designed chuck work surfaces to accommodate specific application requirements.

Technical Specifications

Model:	MWM-850	MWM-853
Dimensions:	30.5 (H) x 39.5 (W) x 80 cm (D)	30.5 (H) x 53 (W) x 95 cm (D)
	12" (H) x 15.5" (W) x 31.5" (D)	12" (H) x 21" (W) x 37.5" (D)
Weight:	70 lbs (32 kg)	100 lbs (45 kg)
Line Voltage:	110/220 Vac, 50/60 Hz, Single Phase	
Air:	5 bar, CDA	

- All other countries and general enquiries:
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MWM-850/853 Manual Wafer Mounting Systems

General Description

AE's MWM-850 and MWM-853 systems provide controlled and repeatable wafer-to-frame tape mounting results. Optimal tape tensioning and bubble-free mounting are critical elements for consistent, reliable results in dicing and singulation processing. With their robust and flexible design, AE's manual wafer mounters are multi-purpose wafer mounting platforms, with standard features and options to handle all wafer and film frame sizes up to 12".

Robust and Easy-to-Use

AE's years of experience in the design and manufacture of field-proven wafer mounting systems are the foundation on which the MWM-850 and MWM-853 are built. Simple to set up and operate, these systems are accurate and user-friendly. With their piston-aided cover-lifting mechanism and ergonomic design, operators find the MWM-850 and MWM-853 systems easy-to-use throughout their shift. Robust mechanical design means reliable wafer mounting, day-in and day-out. Requiring only compressed air and electricity, AE's manual wafer mounters can be used almost anywhere space is available.

MWM-850/853 Features-at-a-Glance

- Chucks Available for All Standard Wafer/Film Frame Sizes, Up to 12":
 - MWM-850 (Up to 8").
 - MWM-853 (8" and 12").
- Compact Desktop Design.
- Built-in Vacuum Generator.
- Closed-loop, Digital Platen Temperature Control.
- Static Eliminator Option.
- UV Tape Option.
- Non-contact Mounting Option.
- Safe, Simple, Accurate Operation.

